



EXPERIMENTAL STUDY OF FLUID FLOW IN MICROCHANNEL

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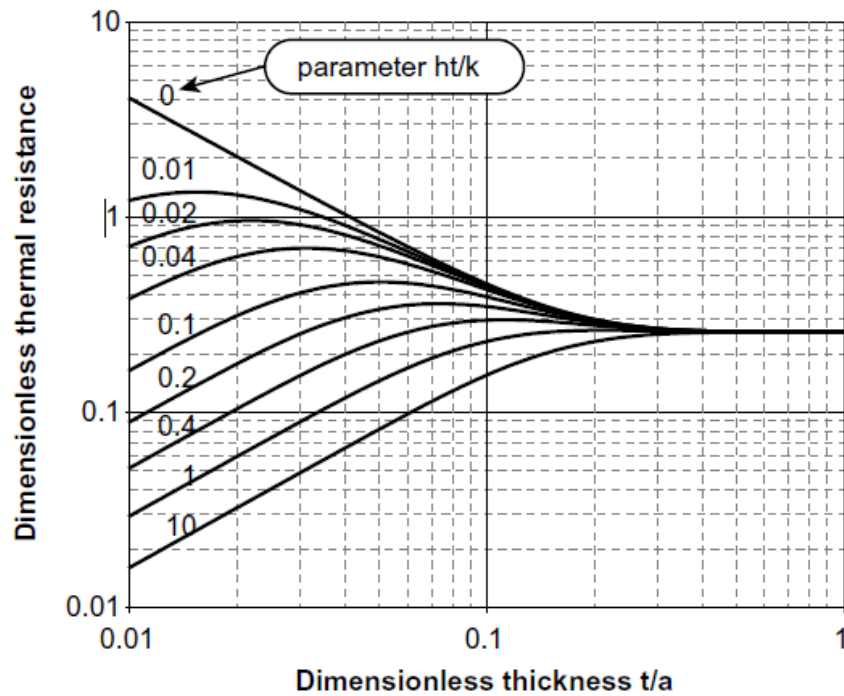
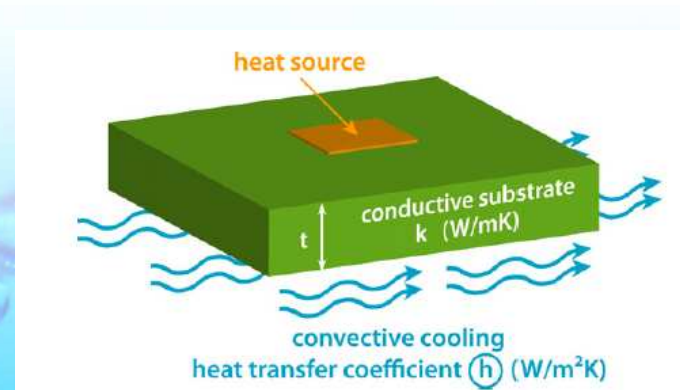
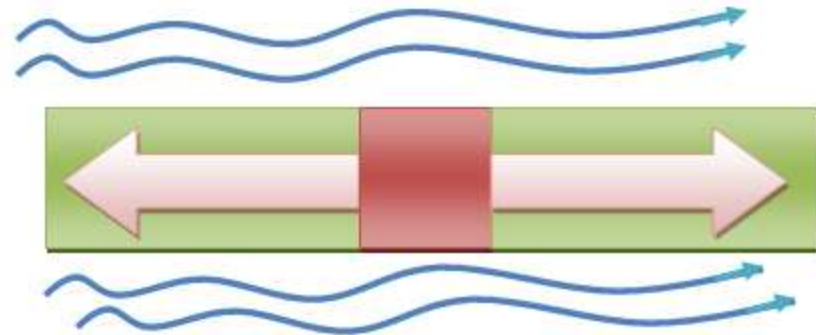


Fig. 1. Typical design curves for conductive and convectively cooled substrate.



B. Vermeersch, G. De Mey / *Microelectronics Reliability* 48 (2008) 734–738

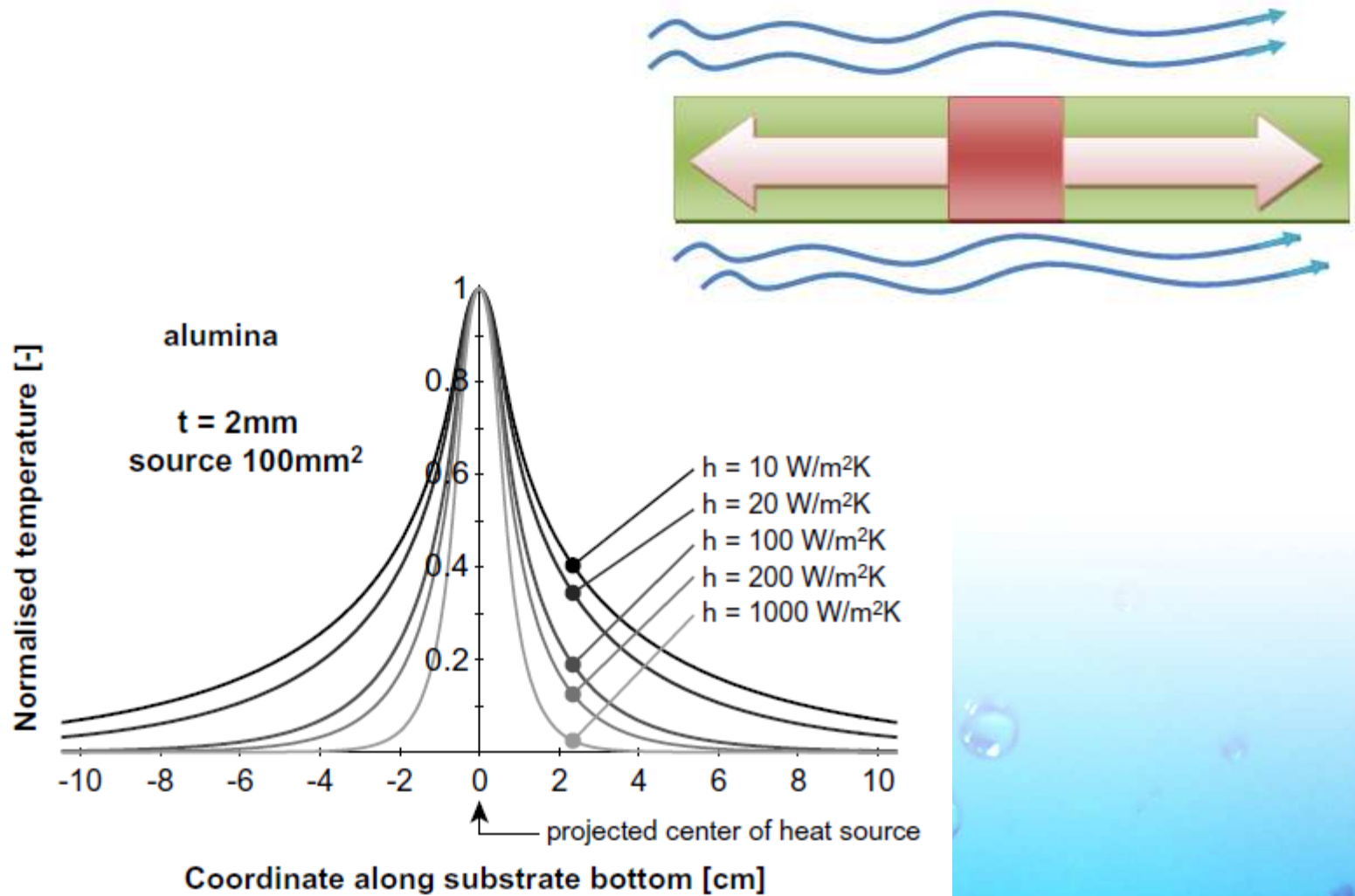


Fig. 8. Exemplary normalised temperature profiles at the bottom of the substrate.

Statement of Purpose

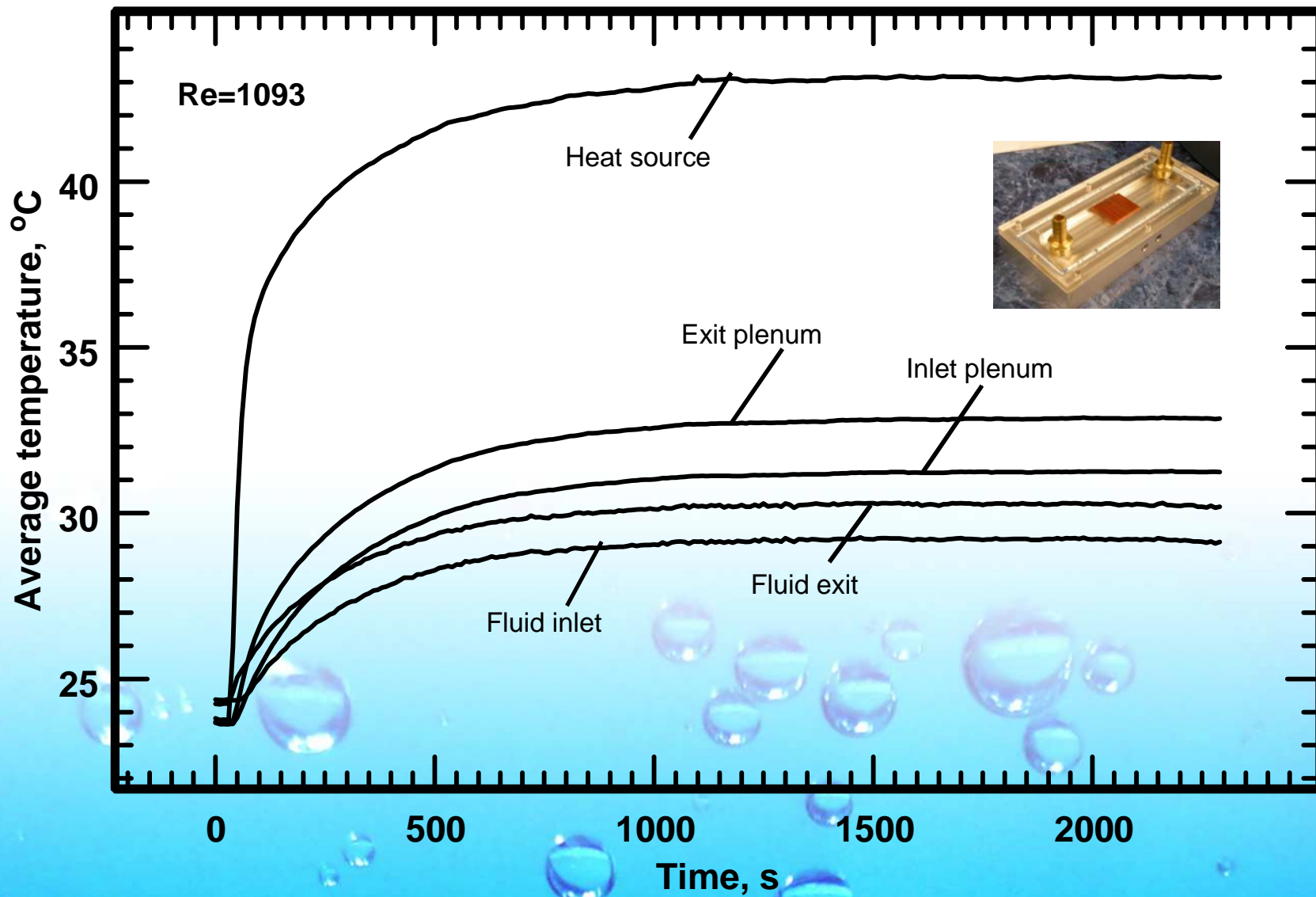
- ▶ Existing studies in literature hypothesizes
 - ▶ symmetrical thermal spreading on the substrate
 - ▶ One-dimensional Longitudinal wall conduction in the substrate
- ▶ To what extent are these hypothesis valid

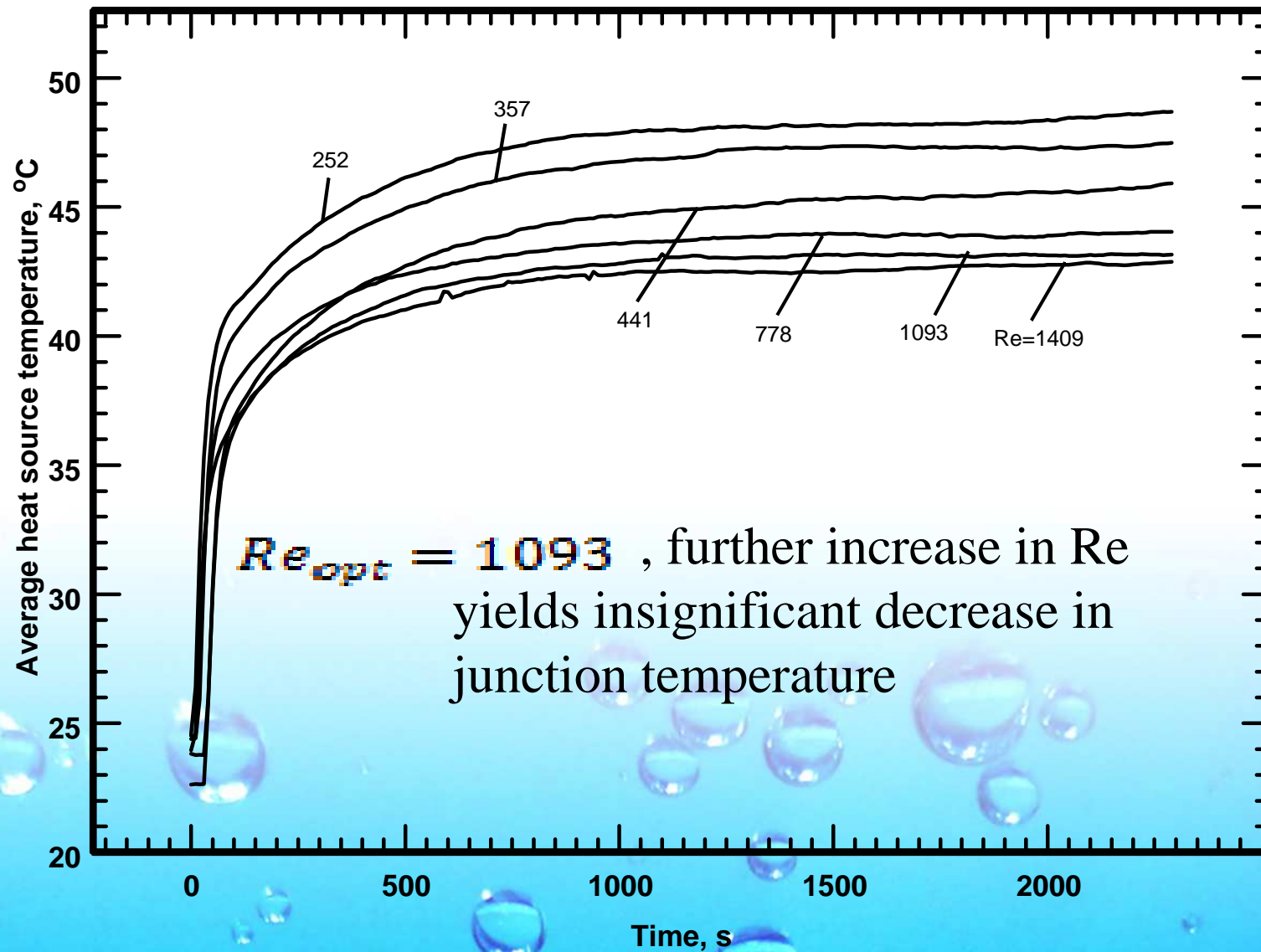
Statement of Purpose

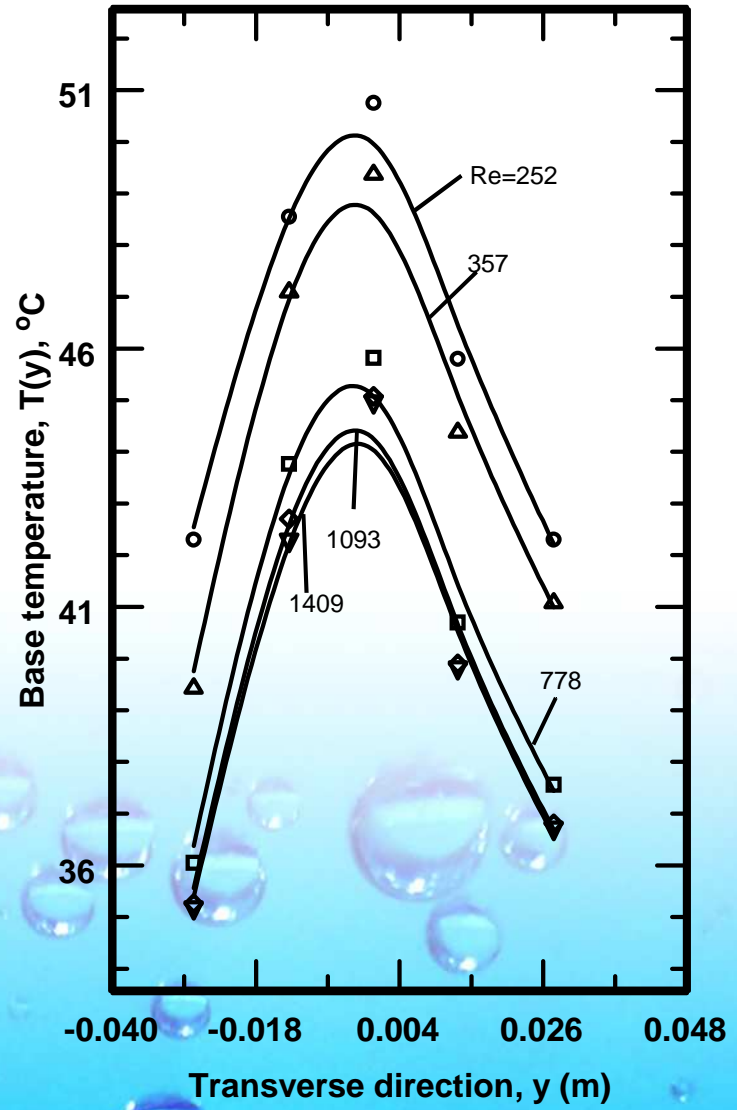
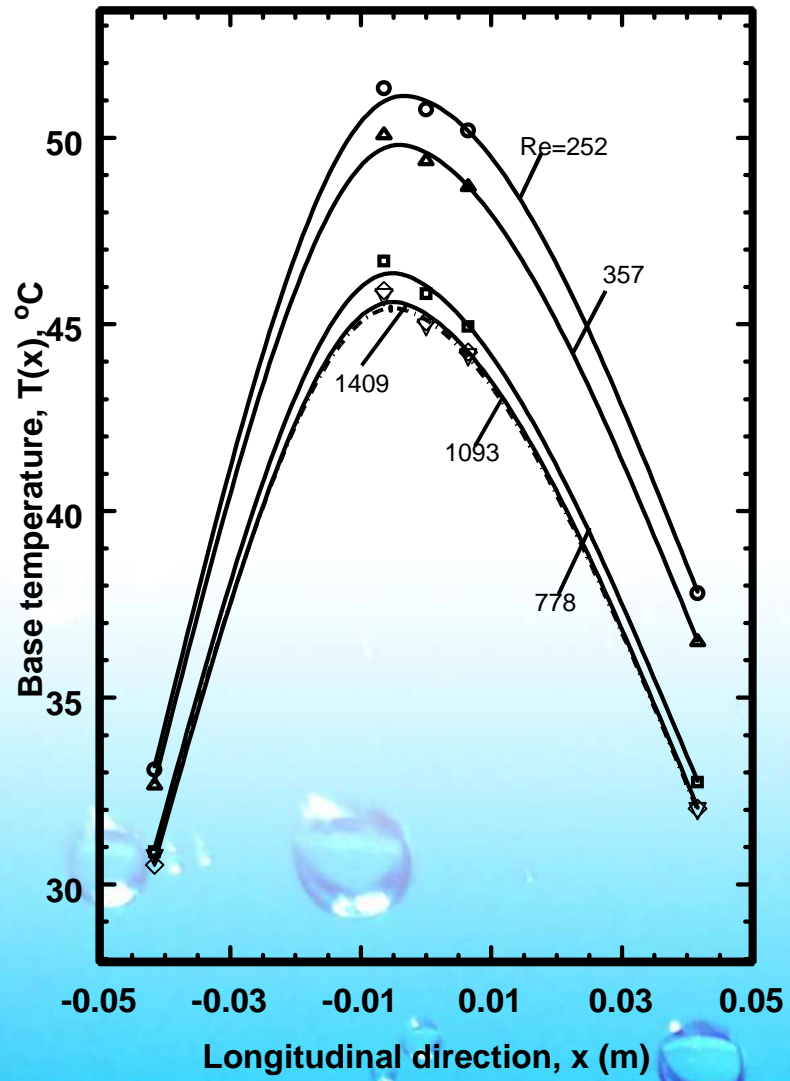
- ▶ Investigation of
 - Nanoparticle-microchannel wall interaction
 - Impact of heat transfer coefficient on longitudinal and transverse wall conduction

Apparatus

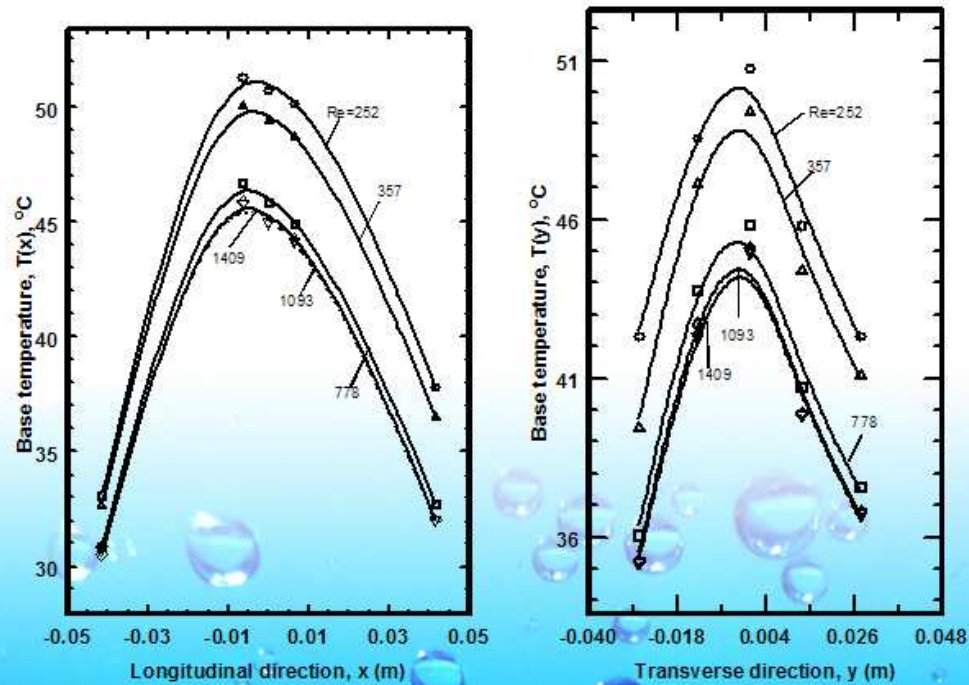








Comparison of temperature profiles



Present study

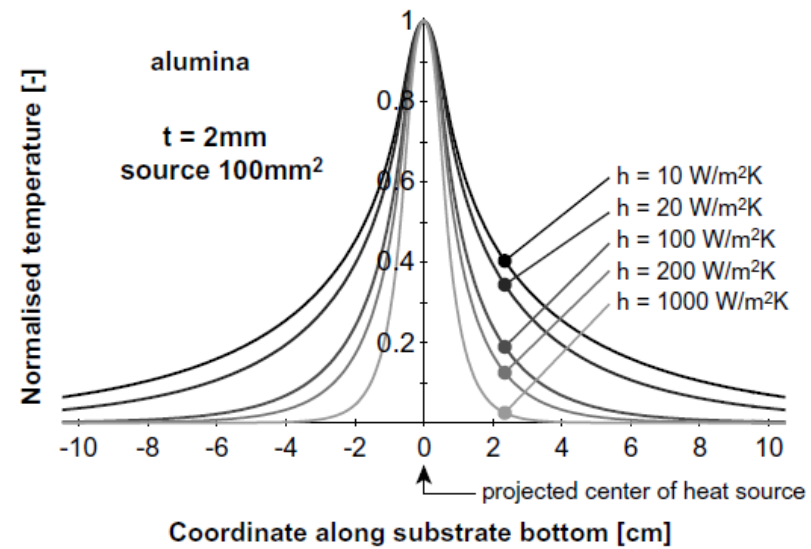
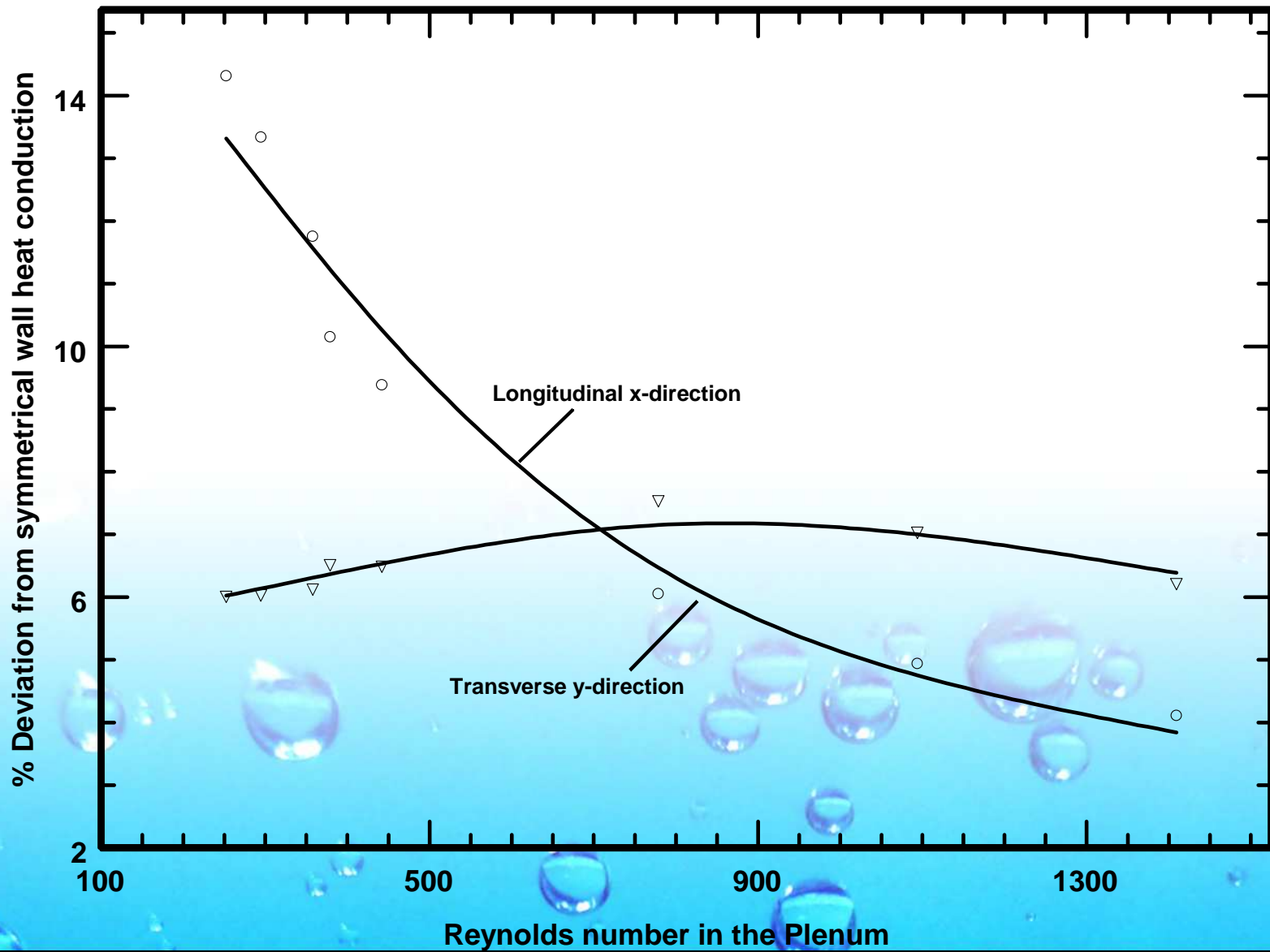
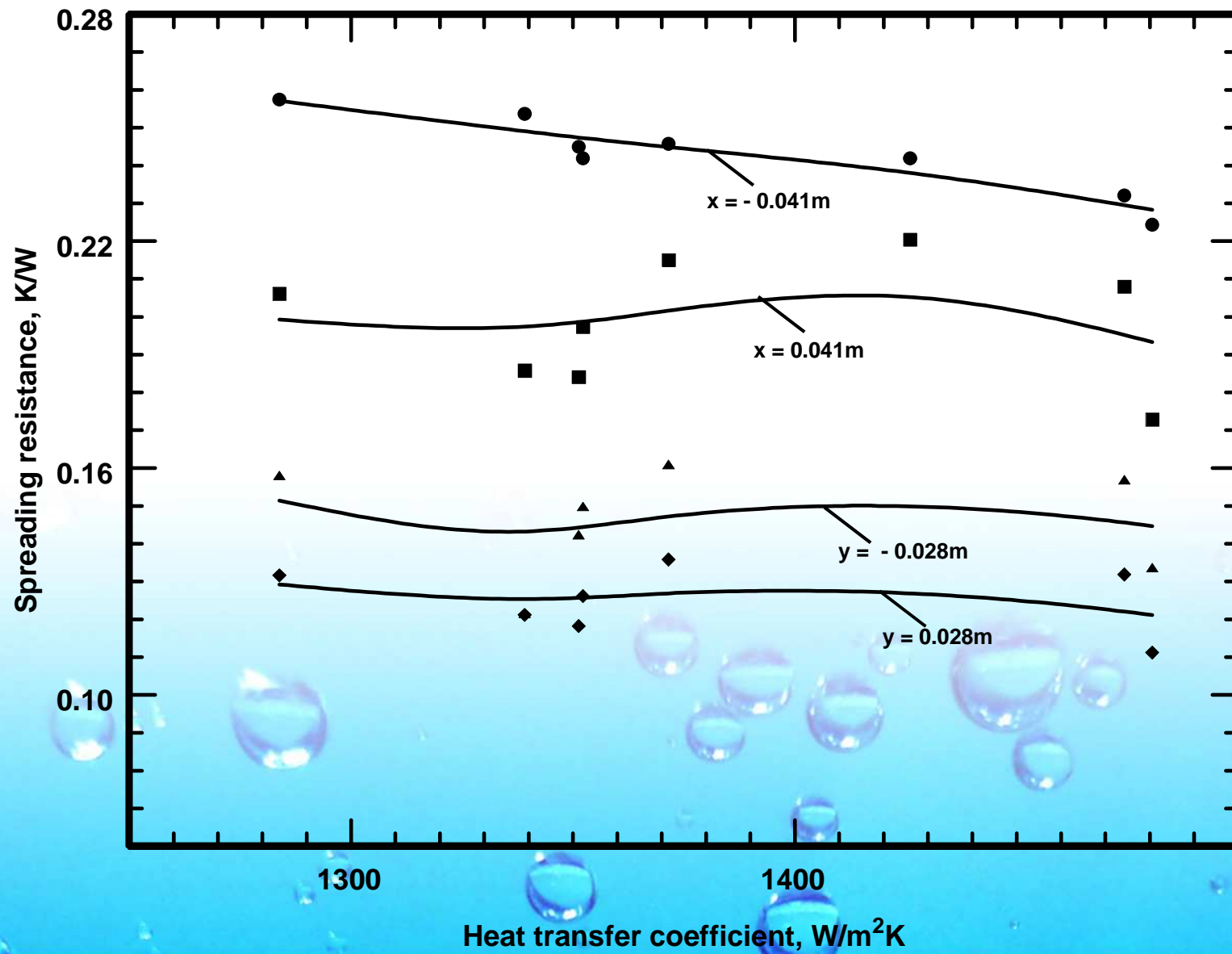
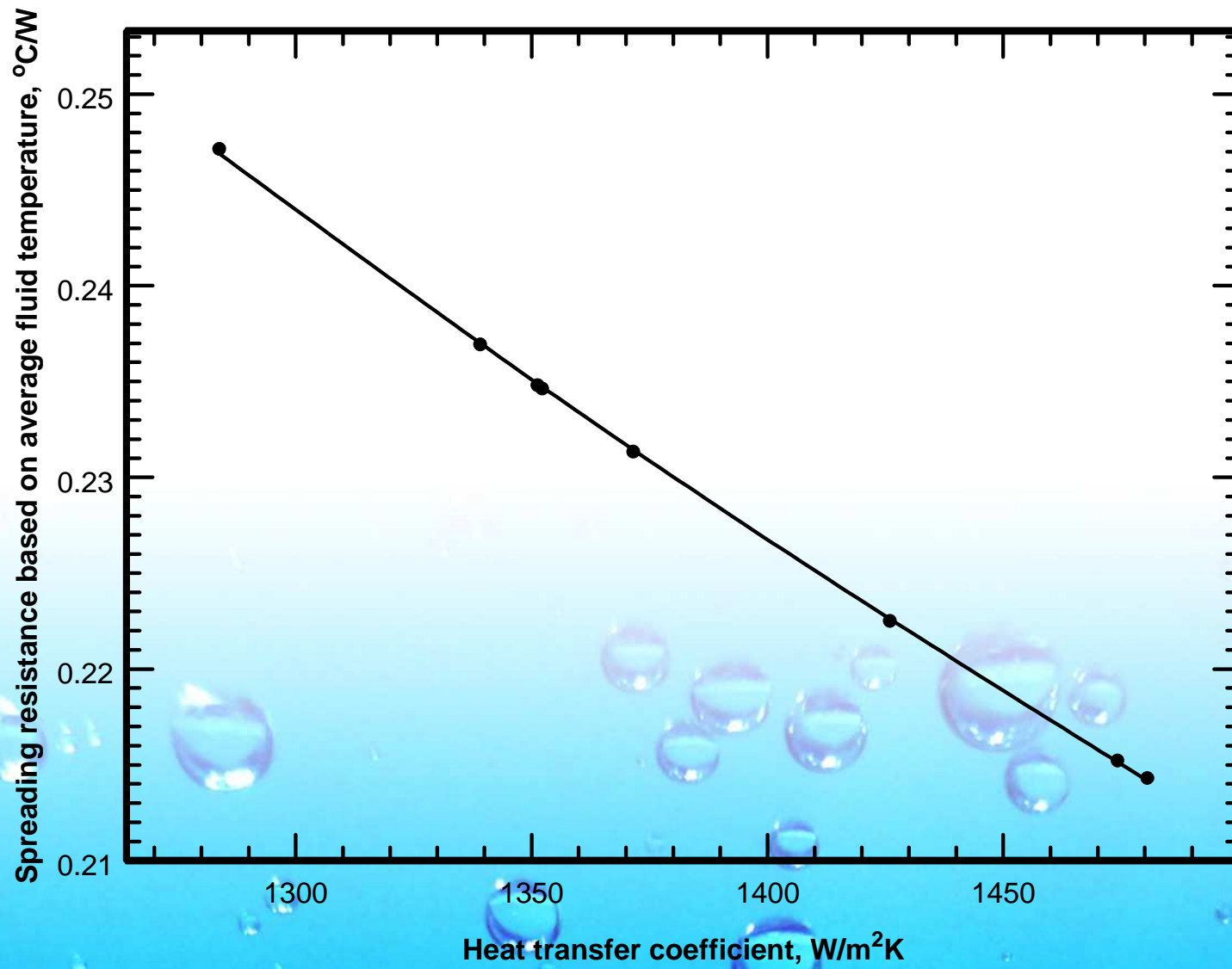


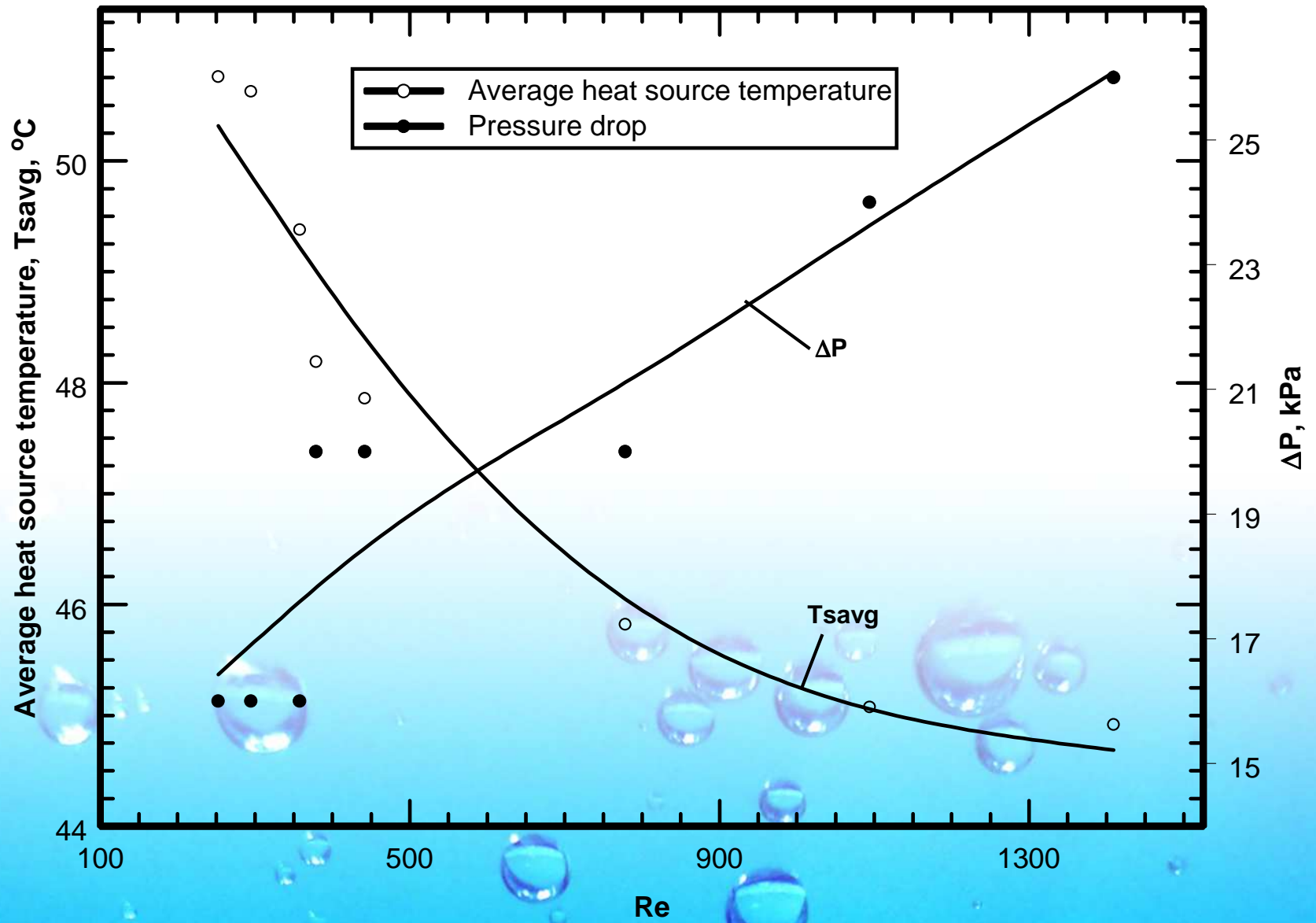
Fig. 8. Exemplary normalised temperature profiles at the bottom of the substrate.

Literature









Conclusion

- ▶ It is observed that the heat transfer coefficient is a weak function of thermal spreading resistance
- ▶ Longitudinal heat conduction in the leading section is strongly influenced by Reynolds number and decreases with increasing Re
- ▶ Longitudinal wall conduction in the trailing section and transverse wall conduction are weak functions of Reynolds number
- ▶ The heat source or junction temperature decreases with increasing Re . There exist an Re beyond which further increase in flow rate results in negligible decrease in junction temperature